PRELIMINARY

_ED750-66-60 epoxy lens type Infrared illuminator LED750-66-60 is a wide

viewing and extremely high output power illuminator assembled with a total of 60 high efficiency AlGaAs LED chips, mounted on a metal stem TO-66 with AIN ceramics and covered with double coated clear silicone and epoxy resin. These devices are designed for high current operation with proper heat sinking to improve thermal conductive efficiency.

Features

- 1) High reliability
- 2) Compact (TO-66) package
- 3) High output power at 750 nm

Applications

- 1) For IR search light
- 2) For CCD lighting
- 3) For night vision light source

Specifications

1) Product name IR illuminator 2) Spec. No. LED750-66-60

3) Chip

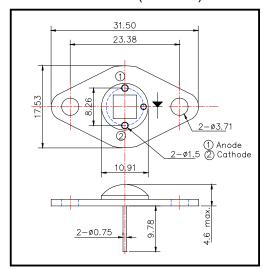
(1) Material **AIGaAs** (2) Peak wavelength 750 nm

4) Package

(1) Stem TO-66 stem with AIN

(2) Lens Clear silicone and epoxy lens

Outer dimension (Unit: mm)



Absolute Maximum Ratings

ltem	Symbol	Maximum Rated Value	Unit	Ambient Temp.	
Power Dissipation	PD	7.8	W	Ta = 25°C	
Forward Current	lf	750	mΑ	Ta = 25°C	
Pulse Forward Current	lfP	3	Α	Ta = 25°C	
Reverse Voltage	Vr	50	V	Ta = 25°C	
Operating Temperature	Topr	-30 ~ +80	°C		
Storage Temperature	Тsтg	-30 ~ +110	°C		
Soldering Temperature	Tsol	240	°C		

[‡]Pulse Forward Current condition: Duty = 1% and Pulse Width = 1 μs.

Flectro-Ontical Characteristics

Item	Symbol	Condition	Minimum	Typical	Maximum	Unit		
Total Radiated Power	Po	IF = 600 mA		1000		mW		
Total Radiated Power	Po	IF = 3 A		4000		mW		
Radiant Intensity	lΕ	IF = 600 mA		450		mW/sr		
Forward Voltage	VF	IF = 600 mA		9.0		V		
Reverse Current	VR	IR = 10 uA	50			V		
Peak Wavelength	λP	IF = 600 mA	735	750	765	nm		
Half Width	Δλ	IF = 600 mA		30		nm		
Viewing Half Angle	. 2Θ/2	IF = 600 mA		±60		deg.		
Rise Time	t _r	IF = 600 mA		100		ns		
Fall Time	t _f	IF = 600 mA		100		ns		

[‡]Heat sink is required thermal resistance <8 K/W

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[‡]Soldering condition: Soldering condition must be completed within 3 seconds at 260°C